

RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS1643 (w/BR1225)	Aug-96	9630 B2	DALLAS	DA083158	N/A	28 MODULE

STRESS/JOB NO.

READPOINT

(Sample Size/No. of Fails)

Hi Temp Storage 70°C, No Bias P-17998, P-178019	<u>0 Hr</u> 90/0	<u>336 Hr</u> 20/0	<u>1K Hr</u> 20/0	<u>Elect. Test</u> 20/0	<u>Cum %</u> 0.0%
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Temp Cycle 0°C to +70°C P-18020	<u>300 ~</u> 35/0	<u>1K ~</u> 35/0	<u>Elect. Test</u> 35/0	<u>Cum %</u> 0.0%
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Moisture Soak 60°C/90% RH P-178021	<u>288 Hr</u> 35/0	<u>960 Hr</u> 35/0	<u>Elect. Test</u> 35/1 F`1	<u>Cum %</u> 2.9%
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Phys. Dimen. <u>P-17997</u> 6/0	Solderability <u>P-17996</u> 24/0
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Failure Mode

F1: Inlkg Lo

Failure Analysis

In process